



POH - AB L1&L2 Flex Cable v1.1.3 - 2-layer Flex-Rigid Board

Material Selection

Polyimide
Permittivity @ 100MHz:
Permittivity @ 1GHz:
Loss Tangent @ 100MHz:
Loss Tangent @ 1GHz:
Lead Free Assembly Compatible

Solder resist colour: green
Silkscreen print colour: white

Surface Finish

On top and bottom layer surfaces:
electroless nickel immersion gold

Holes / Drilling

Drill files contain finished hole diameters
Drilling layer pairs: 1-2

Board Outline

Contour routed with break-away tabs

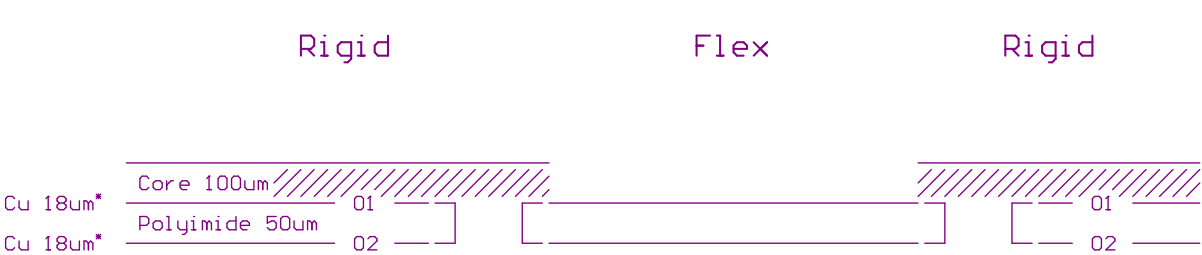
Element Counts
(for reference only)

Nets: 58
Pads: 128
Tracks: 462
Polygons: 1
Holes: 8
Vias: 8

Non-standard Tolerances

Holes sized 0.2mm may be plugged by plating. These are all vias.
For them we do not care the finished hole sizes.

Board Layer Stack / Drill Layer-Pairs



*35um final after plating
Total Laminated Thickness on Rigid Region: 0.3mm +/- 0.05mm !

Controlled Impedance Reference

Diff. trace width/space on bottom layer (microstrip) 60 ohms +/- 10% : 0.150/0.1mm

Layer Name Gerber

Top Overlay .gto
Top Solder Mask .gts
GND .g1
Signal Layer .gbl
Bottom Solder Mask .gbs
Bottom Overlay .gbo
Board Outline .gm1